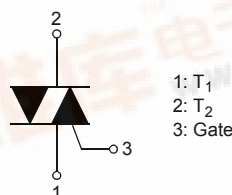
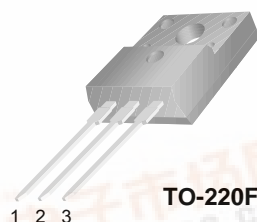




## FKPF2N80

### Application Explanation

- Switching mode power supply, light dimmer, electric flasher unit, hair drier
- TV sets, stereo, refrigerator, washing machine
- Electric blanket, solenoid driver, small motor control
- Photo copier, electric tool



### Bi-Directional Triode Thyristor Planar Silicon

#### Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{\text{DRM}}$	Repetitive Peak Off-State Voltage (Note 1)	800	V

Symbol	Parameter	Conditions	Rating	Units
$I_T(\text{RMS})$	RMS On-State Current	Commercial frequency, sine full wave 360° conduction, $T_C=115^\circ\text{C}$	2	A
$I_{\text{TSM}}$	Surge On-State Current	Sinewave 1 full cycle, peak value, non-repetitive	50Hz: 9 60Hz: 10	A
$I^2t$	$I^2t$ for Fusing	Value corresponding to 1 cycle of halfwave, surge on-state current, $t_p=10\text{ms}$	0.4	$\text{A}^2\text{s}$
$di/dt$	Critical Rate of Rise of On-State Current	$I_G = 2 \times I_{GT}$ , $t_r \leq 100\text{ns}$	50	$\text{A}/\mu\text{s}$
$P_{\text{GM}}$	Peak Gate Power Dissipation		3	W
$P_{\text{G(AV)}}$	Average Gate Power Dissipation		0.3	W
$V_{\text{GM}}$	Peak Gate Voltage		10	V
$I_{\text{GM}}$	Peak Gate Current		1.6	A
$T_J$	Junction Temperature		- 40 ~ 125	$^\circ\text{C}$
$T_{\text{STG}}$	Storage Temperature		- 40 ~ 125	$^\circ\text{C}$
$V_{\text{iso}}$	Isolation Voltage	$T_a=25^\circ\text{C}$ , AC 1 minute, $T_1$ $T_2$ G terminal to case	1500	V

### Thermal Characteristic

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$R_{\text{th(J-A)}}$	Thermal Resistance	Junction to case (Note 4)	-	-	4.5	$^\circ\text{C}/\text{W}$

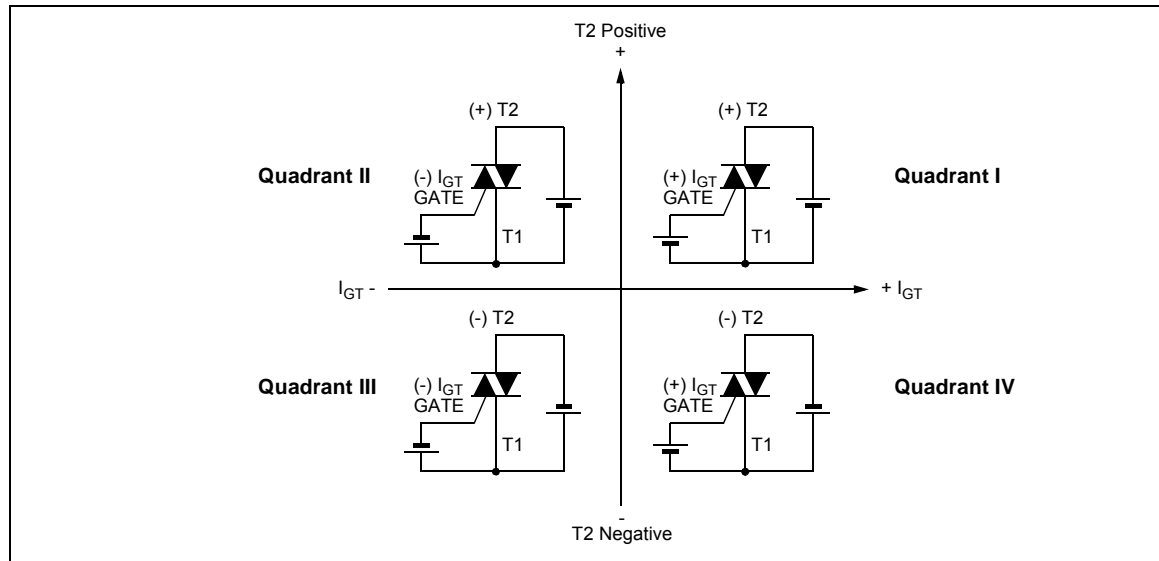
**Electrical Characteristics**  $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter		Test Condition		Min.	Typ.	Max.	Units
I <sub>DRM</sub>	Repetieive Peak Off-State Current		V <sub>DRM</sub> applied		-	-	20	μA
V <sub>TM</sub>	On-State Voltage		T <sub>C</sub> =25°C, I <sub>TM</sub> =3A Instantaneous measurement		-	-	1.6	V
V <sub>GT</sub>	Gate Trigger Voltage <sup>(Note 2)</sup>	I	V <sub>D</sub> =12V, R <sub>L</sub> =20Ω	T2(+), Gate (+)	-	-	1.5	V
		II		T2(+), Gate (-)	-	-	1.5	V
		III		T2(-), Gate (-)	-	-	1.5	V
I <sub>GT</sub>	Gate Trigger Current <sup>(Note 2)</sup>	I	V <sub>D</sub> =12V, R <sub>L</sub> =20Ω	T2(+), Gate (+)	-	-	10	mA
		II		T2(+), Gate (-)	-	-	10	mA
		III		T2(-), Gate (-)	-	-	10	mA
V <sub>GD</sub>	Gate Non-Trigger Voltage		T <sub>J</sub> =125°C, V <sub>D</sub> =1/2V <sub>DRM</sub>		0.2	-	-	V
I <sub>H</sub>	Holding Current		V <sub>D</sub> = 12V, I <sub>TM</sub> = 1A		-	-	10	mA
I <sub>L</sub>	Latching Current	I, III	V <sub>D</sub> = 12V, I <sub>G</sub> = 1.2I <sub>GT</sub>		-	-	10	mA
		II			-	-	10	mA
dv/dt	Critical Rate of Rise of Off-State Voltag		V <sub>DRM</sub> = Rated, T <sub>j</sub> = 125°C, Exponential Rise		-	500	-	V/μs
(dv/dt) <sub>C</sub>	Critical-Rate of Rise of Off-State Commutating Voltage <sup>(Note 3)</sup>				5	-	-	V/μs

**Notes:**

- Gate Open
- Measurement using the gate trigger characteristics measurement circuit
- The critical-rate of rise of the off-state commutating voltage is shown in the table below
- The contact thermal resistance  $R_{\text{TH}(c-f)}$  in case of greasing is  $0.5^\circ\text{C/W}$

$V_{\text{DRM}}$ (V)	Test Condition	Commutating voltage and current waveforms (inductive load)
FKPF2N80	1. Junction Temperature $T_J=125^\circ\text{C}$ 2. Rate of decay of on-state commutating current $(di/dt)_C = -0.5\text{A/ms}$ 3. Peak off-state voltage $V_D = 400\text{V}$	

**Quadrant Definitions for a Triac**

## Typical Curves

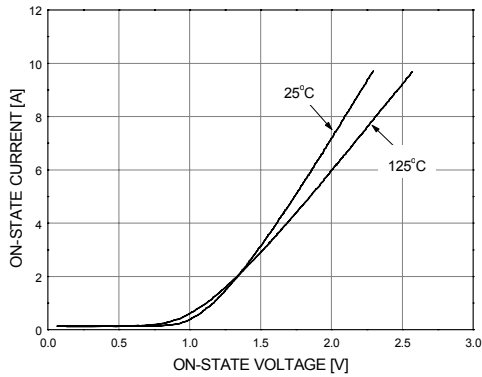


Figure 1. Maximum On-state Characteristics

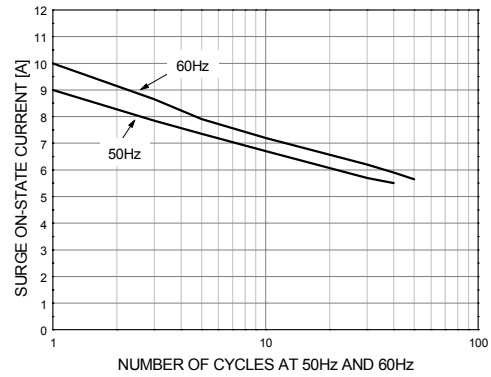


Figure 2. Rated Surge On-state Current

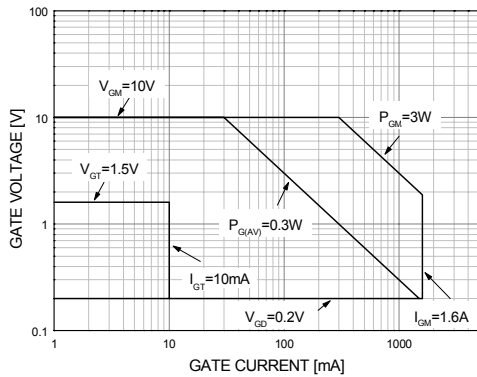


Figure 3. Gate Characteristics

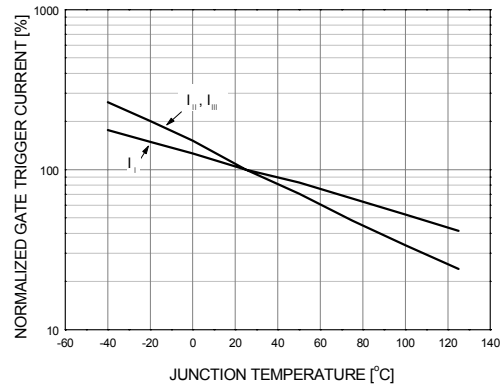


Figure 4. Gate Trigger Current vs  $T_j$

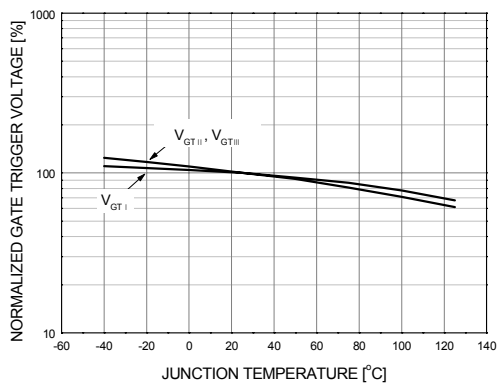


Figure 5. Gate Trigger Voltage vs  $T_j$

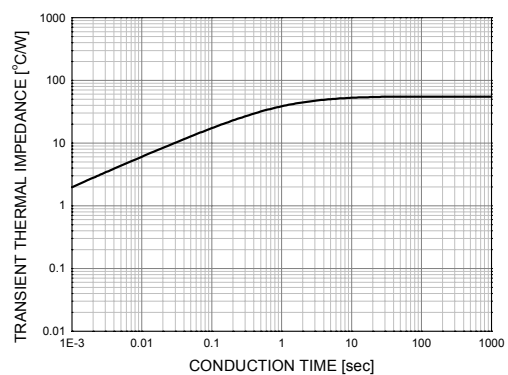
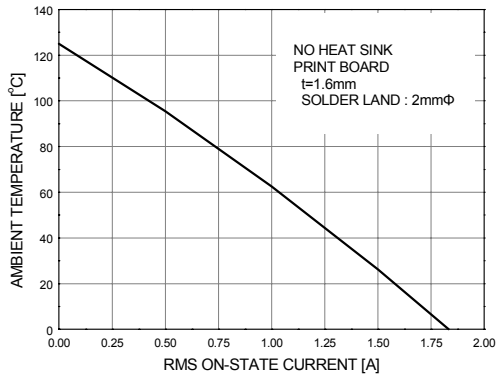
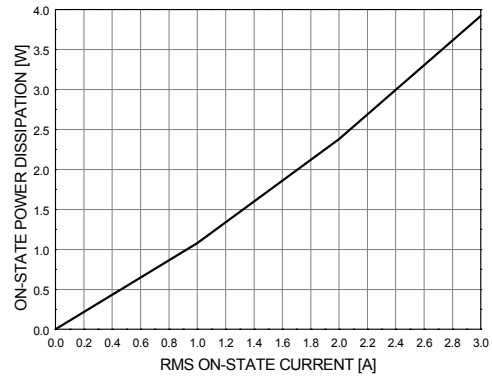


Figure 6. Transient Thermal Impedance

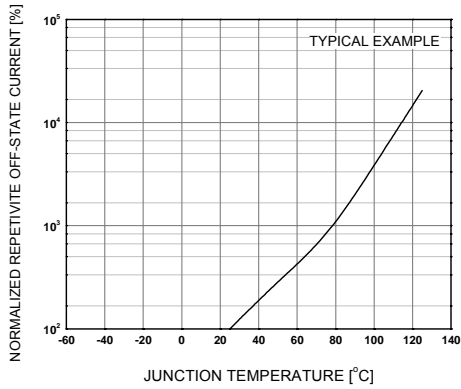
## Typical Curves (Continues)



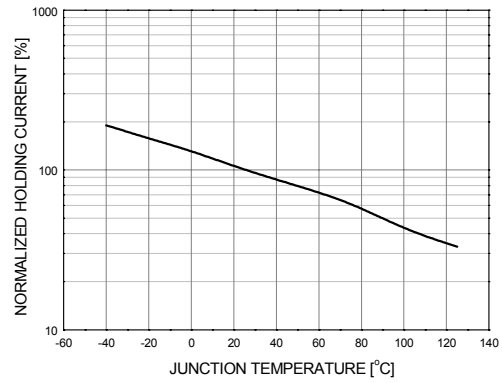
**Figure 7. Allowable Ambient Temperature vs Rms On-state Current**



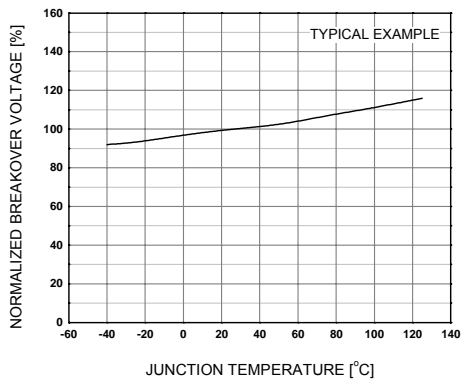
**Figure 8. Maximum On-state Power Dissipation**



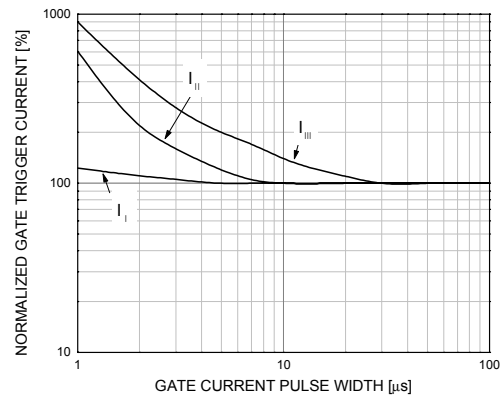
**Figure 9. Repetitive Peak Off-state Current vs Junction Temperature**



**Figure 10. Holding Current vs Junction Temperature**

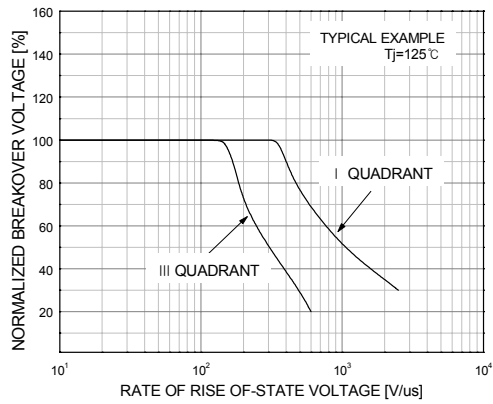


**Figure 11. Breakover Voltage vs Junction Temperature**



**Figure 12. Gate Trigger Current vs Gate Current Pulse Width**

## Typical Curves (Continues)

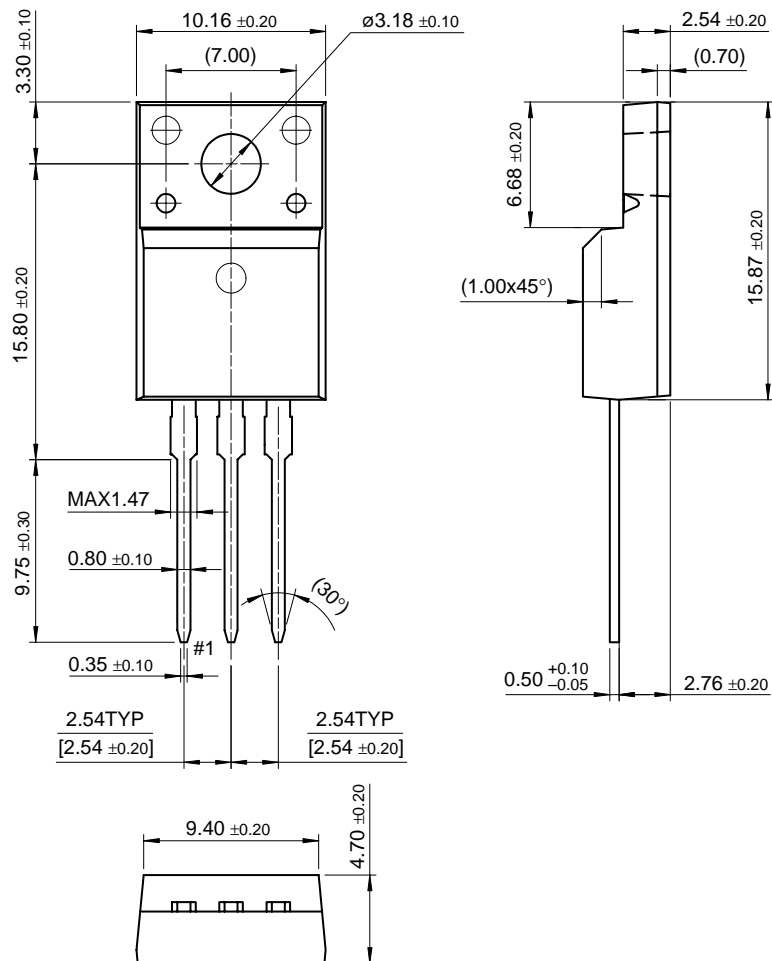


**Figure 13. Breakover Voltage vs  
Rate of Rise of Off-state Voltage**

# Package Dimension

## TO-220F

FKPF2N80



Dimensions in Millimeters

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CROSSVOLT™	FRFET™	MicroFET™	PowerTrench®	SuperSOT™-6
DOME™	GlobalOptoisolator™	MicroPak™	QFET®	SuperSOT™-8
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